



IEEE Topical Meeting on Silicon Monolithic Integrated Circuits in RF Systems

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Call For Papers

IEEE Topical Meetings on Silicon Monolithic Integrated Circuits in RF Systems have been at the forefront of moving Silicon technologies into microwave, millimeter-wave and THz applications – a development now widely accepted, and of great importance. RF CMOS and Si/SiGe BiCMOS technologies are well established in commercial and defense applications. SiRF 2026 will mark the 26th topical meeting on SiRF, with a renewed emphasis on promoting a dialogue between IC designers and researchers promoting non-standard technologies, exploiting the maturity of Silicon processes, but addressing the challenges of tomorrow. The three days of SiRF 2026 will chronicle recent advances in our dynamic field, and provide the platform for developing new ideas, and candid exchange, facilitated by SiRF's single-session format. As in past years, a line-up of reputed invited speakers will stimulate our discussions, with an emphasis on emerging technologies. For more details, visit: www.radiowirelessweek.org/sirf. SiRF 2026 solicits papers in the following focus areas:

1. RF, Millimeter-Wave, and THz Integrated Circuit Front Ends

- RF/mm-Wave/THz Integrated Circuits, Sub-Systems, and Transceivers
- Integrated Circuits for Phased Array, MIMO, and B5G/6G Systems
- Reconfigurable Front Ends, Multi-Band/Ultra-Wideband Circuits and Systems
- AI-Driven and AI-Enabled RF/mm-Wave Circuits and Emerging Applications

2. Wireline/Optical Communication Circuits and SiPho Integrated Circuits

- Broadband Wireline Transmitters, Receivers, and Transceivers
- High-Speed/Broadband Front Ends (TIA, Driver)
- Oscillators, PLLs, Synthesizers, and Signal Generators
- Advanced Techniques for Clock and Data Recovery (CDR)
- Electronic-Photonic Integrated Circuits and Systems

3. High-Speed Data Converters and Mixed-Signal Integrated Circuits

- Nyquist Rate and Oversampling A/D and D/A Converters
- Time-to-Digital and Analog-to-Information Converters
- Digitally-Assisted Analog Integrated Circuits and Calibration Techniques
- Other Advanced Analog/Mixed-Signal Integrated Circuits

4. Device Technologies, Advanced Packaging, and Heterogeneous Integration

- Advanced bulk CMOS, SOI CMOS, FinFET, and SiGe BiCMOS Process Technology and Device Modeling
- Heterogeneous Integration, System-on-Chip, and System-in-Package
- Through-Silicon Vias, RF MEMs, and Micromachining
- Circuit-Package Interaction and Co-Simulation
- Integrated Antennas, Antenna-in-Package, and Metasurfaces
- Advanced Measurement and De-Embedding Techniques

Paper submission instructions can be found at www.radiowirelessweek.org. Submissions should be formatted according to the submission review template available on the RWW website. Authors should indicate preference for oral or poster presentation. All submissions must be received by **23 July 2025**. All accepted papers will be published in a digest and presented papers will be included in the IEEE Xplore® Digital Library. Submissions will be evaluated based on novelty, significance of the work, technical content, interest to the audience, and quality of writing.